

## **STACKED SEMICONDUCTOR DEVICE**

### **ABSTRACT OF THE DISCLOSURE**

A stacked semiconductor device has a substrate having a conductor pattern  
5 and a cavity. A first die is received in the cavity of the cavity of the substrate and is  
electrically connected to the conductor pattern via wires. An adhesive layer is printed  
on a top of the first die. A second die is stacked on the first die via the adhesive layer  
and is electrically connected to the conductor pattern via wires, and An insulating layer  
provided on the substrate, wherein the insulating layer cover the first die and the  
10 second die and has a portion thereof received in the cavity to bond the first die.